



**THE DATASHEET OF  
ISPLSI1048C-50LQI**





## ispLSI<sup>®</sup> 1048C Device Datasheet

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September 2010

# All Devices Discontinued!

Product Change Notifications (PCNs) have been issued to discontinue all devices in this data sheet.

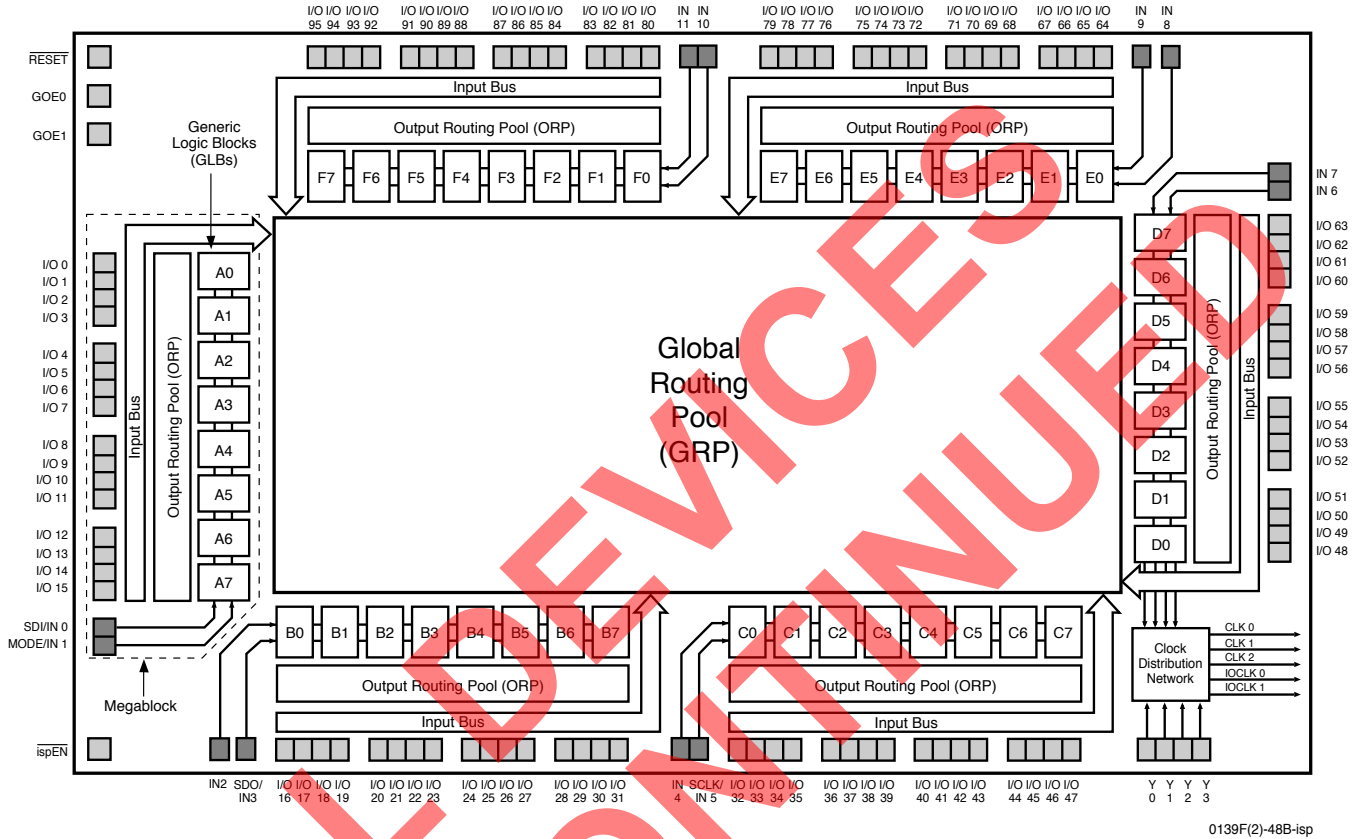
The original datasheet pages have not been modified and do not reflect those changes. Please refer to the table below for reference PCN and current product status.

Product Line	Ordering Part Number	Product Status	Reference PCN
ispLSI 1048C	ispLSI 1048C-50LQ	Discontinued	<a href="#">PCN#13-10</a>
	ispLSI 1048C-70LQ		
	ispLSI 1048C-50LQI		<a href="#">PCN#05A-10</a>
	ispLSI 1048C-50LG/883 5962-9558701MXC		



Functional Block Diagram

Figure 1. ispLSI 1048C Functional Block Diagram



The device also has a 96 I/O cells, each of which is directly connected to an I/O pin. Each I/O cell can be individually programmed to be a combinatorial input, registered input, latched input, output or bi-directional I/O pin with 3-state control. Additionally, all outputs have selectable polarity, active high or active low. The signal voltage levels are TTL-compatible, and the output drivers can source 4 mA or sink 8 mA.

Eight GLBs, 16 I/O cells, two dedicated inputs and one ORP are connected together to make a Megablock as shown in figure 1. The outputs of the eight GLBs are connected to a set of 16 universal I/O cells by the ORP. Each ispLSI 1048C device contains six Megablocks.

The GRP has, as its inputs, the outputs from all of the GLBs and all of the inputs from the bi-directional I/O cells. All of these signals are made available to the inputs of the GLBs. Delays through the GRP have been equalized to minimize timing skew.

Clocks in the ispLSI 1048C device are selected using the Clock Distribution Network. Four dedicated clock pins (Y0, Y1, Y2 and Y3) are brought into the distribution network, and five clock outputs (CLK 0, CLK 1, CLK 2, IOCLK 0 and IOCLK 1) are provided to route clocks to the GLBs and I/O cells. The Clock Distribution Network can also be driven from a special clock GLB (D0 on the ispLSI 1048C device). The logic of this GLB allows the user to create an internal clock from a combination of internal signals.

## Absolute Maximum Ratings <sup>1</sup>

- Supply Voltage  $V_{CC}$  ..... -0.5 to +7.0V
- Input Voltage Applied ..... -2.5 to  $V_{CC} + 1.0V$
- Off-State Output Voltage Applied ..... -2.5 to  $V_{CC} + 1.0V$
- Storage Temperature ..... -65 to 150°C
- Case Temp. with Power Applied ..... -55 to 125°C
- Max. Junction Temp. ( $T_J$ ) with Power Applied ... 150°C

1. Stresses above those listed under the “Absolute Maximum Ratings” may cause permanent damage to the device. Functional operation of the device at these or at any other conditions above those indicated in the operational sections of this specification is not implied (while programming, follow the programming specifications).

## DC Recommended Operating Conditions

SYMBOL	PARAMETER	MIN.	MAX.	UNITS	
$V_{CC}$	Supply Voltage	Commercial $T_A = 0^\circ\text{C to } +70^\circ\text{C}$	4.75	5.25	V
		Industrial $T_A = -40^\circ\text{C to } +85^\circ\text{C}$	4.5	5.5	
		Military/883 $T_C = -55^\circ\text{C to } +125^\circ\text{C}$	4.5	5.5	
$V_{IL}$	Input Low Voltage	0	0.8	V	
$V_{IH}$	Input High Voltage	2.0	$V_{CC} + 1$	V	

Table 2- 0005Aisp w/mil.eps

## Capacitance ( $T_A=25^\circ\text{C}$ , $f=1.0$ MHz)

SYMBOL	PARAMETER	□□MAXIMUM	UNITS	TEST CONDITIONS	
$C_1$	Dedicated Input Capacitance	Commercial/Industrial	8	pf	$V_{CC}=5.0V, V_{IN}=2.0V$
		Military	10	pf	$V_{CC}=5.0V, V_{IN}=2.0V$
$C_2$	I/O and Clock Capacitance	10	pf	$V_{CC}=5.0V, V_{I/O}, V_Y=2.0V$	

1. Characterized but not 100% tested.

Table 2- 0006

## Data Retention Specifications

PARAMETER	MINIMUM	MAXIMUM	UNITS
Data Retention	20	—	Years
Erase/Reprogram Cycles	10000	—	Cycles

Table 2- 0008B

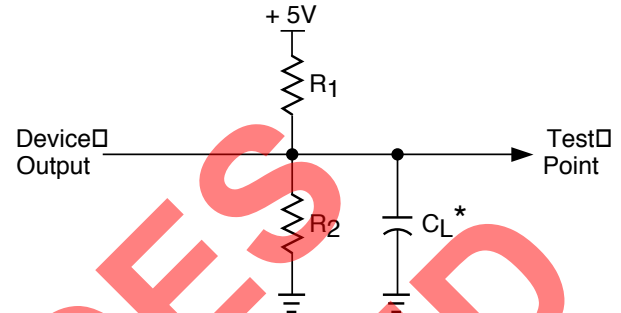
**Switching Test Conditions**

Input Pulse Levels	GND to 3.0V
Input Rise and Fall Time	≤ 3ns 10% to 90%
Input Timing Reference Levels	1.5V
Output Timing Reference Levels	1.5V
Output Load	See figure 2

3-state levels are measured 0.5V from steady-state active level.

Table 2- 0003

**Figure 2. Test Load**



\*CL includes Test Fixture and Probe Capacitance.

**Output Load Conditions (see figure 2)**

Test Condition	R1	R2	CL
A	470Ω	390Ω	35pF
B	Active High	∞	390Ω
	Active Low	470Ω	390Ω
C	Active High to Z at $V_{OH} - 0.5V$	∞	390Ω
	Active Low to Z at $V_{OL} + 0.5V$	470Ω	390Ω

Table 2- 0004A

**DC Electrical Characteristics**

**Over Recommended Operating Conditions**

SYMBOL	PARAMETER	CONDITION	MIN.	TYP. <sup>3</sup>	MAX.	UNITS	
<b>VOL</b>	Output Low Voltage	$I_{OL} = 8 \text{ mA}$	-	-	0.4	V	
<b>VOH</b>	Output High Voltage	$I_{OH} = -4 \text{ mA}$	2.4	-	-	V	
<b>IIL</b>	Input or I/O Low Leakage Current	$0V \leq V_{IN} \leq V_{IL} \text{ (MAX.)}$	-	-	-10	μA	
<b>IiH</b>	Input or I/O High Leakage Current	$3.5V \leq V_{IN} \leq V_{CC}$	-	-	10	μA	
<b>IIL-isp</b>	ispEN Input Low Leakage Current	$0V \leq V_{IN} \leq V_{IL} \text{ (MAX.)}$	-	-	-150	μA	
<b>IIL-PU</b>	I/O Active Pull-Up Current	$0V \leq V_{IN} \leq V_{IL}$	-	-	-150	μA	
<b>IOS<sup>1</sup></b>	Output Short Circuit Current	$V_{CC} = 5V, V_{OUT} = 0.5V$	-	-	-200	mA	
<b>ICC<sup>2,4</sup></b>	Operating Power Supply Current	$V_{IL} = 0.5V, V_{IH} = 3.0V$	Commercial	-	165	235	mA
		$f_{TOGGLE} = 1 \text{ MHz}$	Industrial/Military	-	165	260	mA

- One output at a time for a maximum duration of one second.  $V_{out} = 0.5V$  was selected to avoid test problems by tester ground degradation. Characterized but not 100% tested.
- Measured using twelve 16-bit counters.
- Typical values are at  $V_{CC} = 5V$  and  $T_A = 25^\circ C$ .
- Maximum  $I_{CC}$  varies widely with specific device configuration and operating frequency. Refer to the Power Consumption section of this datasheet and Thermal Management section of the Lattice Semiconductor Data Book or CD-ROM to estimate maximum  $I_{CC}$ .

Table 2- 0007A-48-isp

External Timing Parameters

Over Recommended Operating Conditions

PARAMETER	TEST <sup>4</sup> COND.	# <sup>2</sup>	DESCRIPTION <sup>1</sup>	-70		-50		UNITS
				MIN.	MAX.	MIN.	MAX.	
t <sub>pd1</sub>	A	1	Data Propagation Delay, 4PT bypass, ORP bypass	-	16.0	-	22.0	ns
t <sub>pd2</sub>	A	2	Data Propagation Delay	-	19.0	-	26.0	ns
f <sub>max</sub> (Int.)	A	3	Clock Frequency with Internal Feedback <sup>3</sup>	70.4	-	50.3	-	MHz
f <sub>max</sub> (Ext.)	-	4	Clock Frequency with External Feedback ( $\frac{1}{t_{su2} + t_{co1}}$ )	47.6	-	34.5	-	MHz
f <sub>max</sub> (Tog.)	-	5	Clock Frequency, Max Toggle ( $\frac{1}{t_{wh} + t_{wl}}$ )	83.3	-	58.8	-	MHz
t <sub>su1</sub>	-	6	GLB Reg. Setup Time before Clock, 4PT bypass	9.5	-	13.0	-	ns
t <sub>co1</sub>	A	7	GLB Reg. Clock to Output Delay, ORP bypass	-	10.0	-	14.0	ns
t <sub>h1</sub>	-	8	GLB Reg. Hold Time after Clock, 4 PT bypass	0	-	0	-	ns
t <sub>su2</sub>	-	9	GLB Reg. Setup Time before Clock	11.0	-	15.0	-	ns
t <sub>co2</sub>	-	10	GLB Reg. Clock to Output Delay	-	11.5	-	16.0	ns
t <sub>h2</sub>	-	11	GLB Reg. Hold Time after Clock	0	-	0	-	ns
t <sub>r1</sub>	A	12	Ext. Reset Pin to Output Delay	-	15.0	-	20.5	ns
t <sub>rw1</sub>	-	13	Ext. Reset Pulse Duration	10.0	-	13.5	-	ns
t <sub>ptoen</sub>	B	14	Input to Output Enable	-	20.0	-	27.5	ns
t <sub>ptodis</sub>	C	15	Input to Output Disable	-	20.0	-	27.5	ns
t <sub>goeen</sub>	B	16	Global OE Output Enable	-	15.0	-	20.5	ns
t <sub>goedis</sub>	C	17	Global OE Output Disable	-	15.0	-	20.5	ns
t <sub>wh</sub>	-	20	Ext. Sync. Clock Pulse Duration, High	6.0	-	8.5	-	ns
t <sub>wl</sub>	-	21	Ext. Sync. Clock Pulse Duration, Low	6.0	-	8.5	-	ns
t <sub>su3</sub>	-	22	I/O Reg. Setup Time before Ext. Sync. Clock (Y2, Y3)	2.0	-	3.0	-	ns
t <sub>h3</sub>	-	23	I/O Reg. Hold Time after Ext. Sync. Clock (Y2, Y3)	6.5	-	9.0	-	ns

1. Unless noted otherwise, all parameters use a GRP load of 4 GLBs, 20 PTXOR path, ORP and Y0 clock.
2. Refer to Timing Model in this data sheet for further details.
3. Standard 16-Bit counter using GRP feedback.
4. Reference Switching Test Conditions section.

Table 2- 0030-48C/70, 50

Internal Timing Parameters<sup>1</sup>

PARAMETER	# <sup>2</sup>	DESCRIPTION	-70		-50		UNITS
			MIN.	MAX.	MIN.	MAX.	
<b>Inputs</b>							
t <sub>iobp</sub>	24	I/O Register Bypass	–	3.1	–	4.3	ns
t <sub>iolat</sub>	25	I/O Latch Delay	–	4.0	–	5.5	ns
t <sub>iosu</sub>	26	I/O Register Setup Time before Clock	6.5	–	9.1	–	ns
t <sub>ioh</sub>	27	I/O Register Hold Time after Clock	0.1	–	0.3	–	ns
t <sub>ioco</sub>	28	I/O Register Clock to Out Delay	–	3.4	–	4.6	ns
t <sub>ior</sub>	29	I/O Register Reset to Out Delay	–	3.7	–	5.1	ns
t <sub>din</sub>	30	Dedicated Input Delay	–	5.4	–	7.4	ns
<b>GRP</b>							
t <sub>grp1</sub>	31	GRP Delay, 1 GLB Load	–	4.5	–	6.2	ns
t <sub>grp4</sub>	32	GRP Delay, 4 GLB Loads	–	4.9	–	6.7	ns
t <sub>grp8</sub>	33	GRP Delay, 8 GLB Loads	–	5.8	–	8.0	ns
t <sub>grp16</sub>	34	GRP Delay, 16 GLB Loads	–	7.6	–	10.5	ns
t <sub>grp48</sub>	35	GRP Delay, 48 GLB Loads	–	16.5	–	22.7	ns
<b>GLB</b>							
t <sub>4ptbp</sub>	36	4 Product Term Bypass Path Delay	–	4.0	–	5.5	ns
t <sub>1ptxor</sub>	37	1 Product Term/XOR Path Delay	–	4.9	–	6.7	ns
t <sub>20ptxor</sub>	38	20 Product Term/XOR Path Delay	–	5.5	–	7.5	ns
t <sub>xoradj</sub>	39	XOR Adjacent Path Delay <sup>3</sup>	–	6.5	–	8.9	ns
t <sub>gbp</sub>	40	GLB Register Bypass Delay	–	0.9	–	1.2	ns
t <sub>gsu</sub>	41	GLB Register Setup Time before Clock	2.9	–	3.9	–	ns
t <sub>gh</sub>	42	GLB Register Hold Time after Clock	5.3	–	7.3	–	ns
t <sub>gco</sub>	43	GLB Register Clock to Output Delay	–	1.5	–	2.3	ns
t <sub>gro</sub>	44	GLB Register Reset to Output Delay	–	2.1	–	2.8	ns
t <sub>ptre</sub>	45	GLB Product Term Reset to Register Delay	–	8.1	–	11.1	ns
t <sub>ptoe</sub>	46	GLB Product Term Output Enable to I/O Cell Delay	–	7.0	–	9.6	ns
t <sub>ptck</sub>	47	GLB Product Term Clock Delay	2.5	6.0	3.4	8.2	ns
<b>ORP</b>							
t <sub>orp</sub>	48	ORP Delay	–	2.5	–	3.4	ns
t <sub>orpbp</sub>	49	ORP Bypass Delay	–	1.0	–	1.4	ns

1. Internal Timing Parameters are not tested and are for reference only.

Table 2- 0036-48C/70, 50

2. Refer to Timing Model in this data sheet for further details.

3. The XOR adjacent path can only be used by hard macros.

Internal Timing Parameters<sup>1</sup>

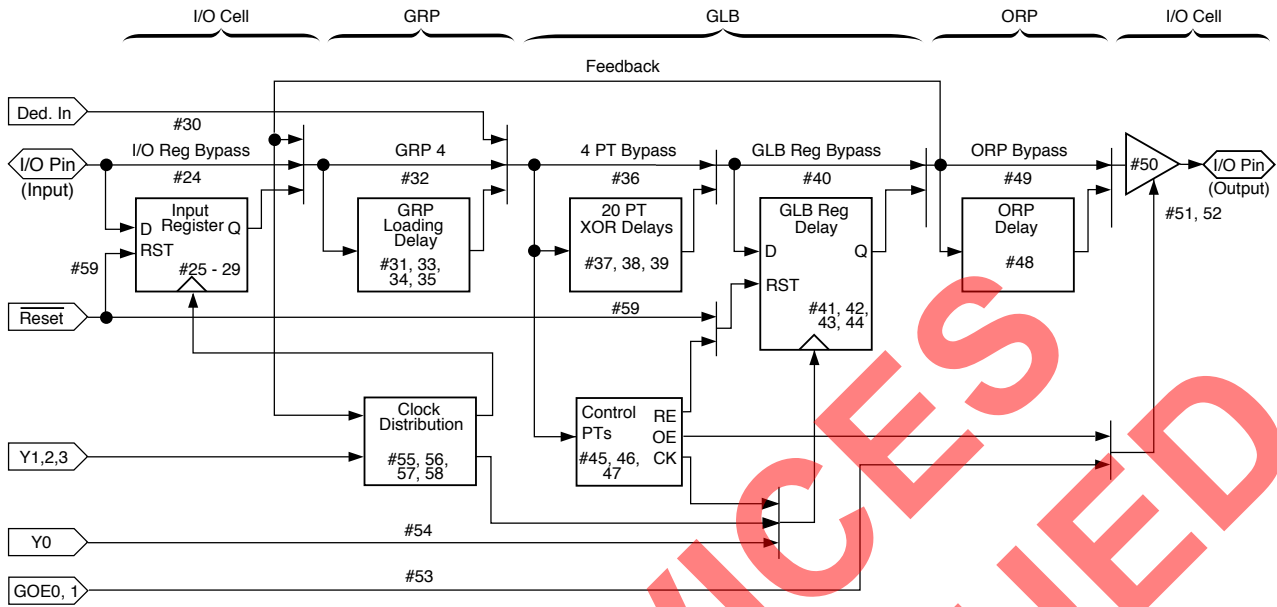
ispLSI 1048C Timing Model

PARAMETER	# <sup>2</sup>	DESCRIPTION	-70		-50		UNITS
			MIN.	MAX.	MIN.	MAX.	
<b>Outputs</b>							
t <sub>ob</sub>	50	Output Buffer Delay	–	2.1	–	2.9	ns
t <sub>oen</sub>	51	I/O Cell OE to Output Enabled	–	5.0	–	6.9	ns
t <sub>odis</sub>	52	I/O Cell OE to Output Disabled	–	5.0	–	6.9	ns
t <sub>goe</sub>	53	Global OE	–	10.0	–	13.6	ns
<b>Clocks</b>							
t <sub>gy0</sub>	54	Clock Delay, Y0 to Global GLB Clock Line (Ref. clock)	5.4	5.4	7.4	7.4	ns
t <sub>gy1/2</sub>	55	Clock Delay, Y1 or Y2 to Global GLB Clock Line	4.5	6.4	6.1	8.7	ns
t <sub>gcp</sub>	56	Clock Delay, Clock GLB to Global GLB Clock Line	1.9	5.5	2.6	7.6	ns
t <sub>ioy2/3</sub>	57	Clock Delay, Y2 or Y3 to I/O Cell Global Clock Line	4.5	6.4	6.1	8.7	ns
t <sub>iocp</sub>	58	Clock Delay, Clock GLB to I/O Cell Global Clock Line	1.9	5.5	2.6	7.6	ns
<b>Global Reset</b>							
t <sub>gr</sub>	59	Global Reset to GLB and I/O Registers	–	8.3	–	11.4	ns

1. Internal Timing Parameters are not tested and are for reference only.

Table 2- 0037-48C/70, 50

ALL DEVICES DISCONTINUED



0491A/48

**Derivations of  $t_{su}$ ,  $t_h$  and  $t_{co}$  from the Product Term Clock<sup>1</sup>**

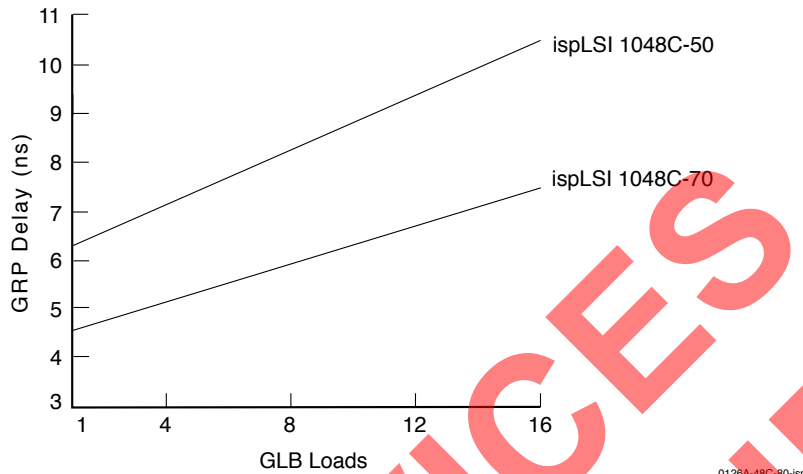
$$\begin{aligned}
 t_{su} &= \text{Logic} + \text{Reg } s_u - \text{Clock (min)} \\
 &= (t_{iobp} + t_{grp4} + t_{20ptxor}) + (t_{gsu}) - (t_{iobp} + t_{grp4} + t_{ptck(min)}) \\
 &= (\#24 + \#32 + \#38) + (\#41) - (\#24 + \#32 + \#47) \\
 5.9 \text{ ns} &= (3.1 + 4.9 + 5.5) + (2.9) - (3.1 + 4.9 + 2.5) \\
 t_h &= \text{Clock (max)} + \text{Reg } h - \text{Logic} \\
 &= (t_{iobp} + t_{grp4} + t_{ptck(max)}) + (t_{gh}) - (t_{iobp} + t_{grp4} + t_{20ptxor}) \\
 &= (\#24 + \#32 + \#47) + (\#42) - (\#24 + \#32 + \#38) \\
 5.8 \text{ ns} &= (3.1 + 4.9 + 6.0) + (5.3) - (3.1 + 4.9 + 5.5) \\
 t_{co} &= \text{Clock (max)} + \text{Reg } c_o + \text{Output} \\
 &= (t_{iobp} + t_{grp4} + t_{ptck(max)}) + (t_{gco}) + (t_{orp} + t_{ob}) \\
 &= (\#24 + \#32 + \#47) + (\#43) + (\#48 + \#50) \\
 20.1 \text{ ns} &= (3.1 + 4.9 + 6.0) + (1.5) + (2.5 + 2.1)
 \end{aligned}$$

**Derivations of  $t_{su}$ ,  $t_h$  and  $t_{co}$  from the Clock GLB<sup>1</sup>**

$$\begin{aligned}
 t_{su} &= \text{Logic} + \text{Reg } s_u - \text{Clock (min)} \\
 &= (t_{iobp} + t_{grp4} + t_{20ptxor}) + (t_{gsu}) - (t_{gy0(min)} + t_{gco} + t_{gcp(min)}) \\
 &= (\#24 + \#32 + \#38) + (\#41) - (\#54 + \#43 + \#56) \\
 7.6 \text{ ns} &= (3.1 + 4.9 + 5.5) + (2.9) - (5.4 + 1.5 + 1.9) \\
 t_h &= \text{Clock (max)} + \text{Reg } h - \text{Logic} \\
 &= (t_{gy0(max)} + t_{gco} + t_{gcp(max)}) + (t_{gh}) - (t_{iobp} + t_{grp4} + t_{20ptxor}) \\
 &= (\#54 + \#43 + \#56) + (\#42) - (\#24 + \#32 + \#38) \\
 4.2 \text{ ns} &= (5.4 + 1.5 + 5.5) + (5.3) - (3.1 + 4.9 + 5.5) \\
 t_{co} &= \text{Clock (max)} + \text{Reg } c_o + \text{Output} \\
 &= (t_{gy0(max)} + t_{gco} + t_{gcp(max)}) + (t_{gco}) + (t_{orp} + t_{ob}) \\
 &= (\#54 + \#43 + \#56) + (\#43) + (\#48 + \#50) \\
 18.5 \text{ ns} &= (5.4 + 1.5 + 5.5) + (1.5) + (2.5 + 2.1)
 \end{aligned}$$

1. Calculations are based upon timing specifications for the ispLSI 1048C-70

**Maximum GRP Delay vs GLB Loads**

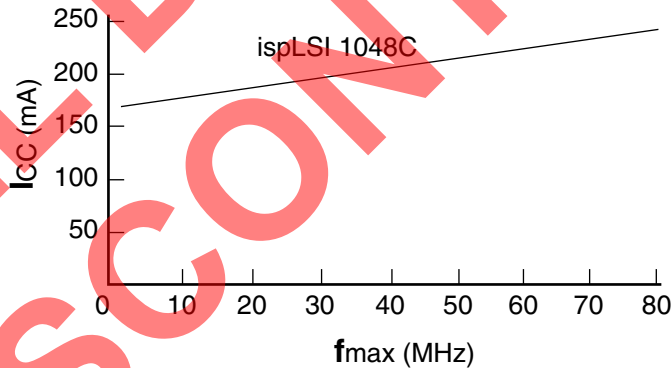


**Power Consumption**

Power consumption in the ispLSI 1048C device depends on two primary factors: the speed at which the device is operating, and the number of Product Terms used. Figure 3 shows the relationship between power and operating speed.

Figure 3 shows the relationship between power and operating speed.

**Figure 3. Typical Device Power Consumption vs fmax**



Notes: Configuration of Twelve 16-bit Counters  
Typical Current at 5V, 25°C

ICC can be estimated for the ispLSI 1048C using the following equation:

$$I_{CC} = 73 + (\# \text{ of PTs} * 0.23) + (\# \text{ of nets} * \text{Max. freq} * 0.010) \text{ where:}$$

# of PTs = Number of Product Terms used in design

# of nets = Number of Signals used in device

Max. freq = Highest Clock Frequency to the device

The ICC estimate is based on typical conditions (VCC = 5.0V, room temperature) and an assumption of 2 GLB loads on average exists. These values are for estimates only. Since the value of ICC is sensitive to operating conditions and the program in the device, the actual ICC should be verified.

0127A-48C-80-isp

Pin Description

NAME	PQFP PIN NUMBERS	DESCRIPTION
I/O 0 - I/O 5 I/O 6 - I/O 11 I/O 12 - I/O 17 I/O 18 - I/O 23 I/O 24 - I/O 29 I/O 30 - I/O 35 I/O 36 - I/O 41 I/O 42 - I/O 47 I/O 48 - I/O 53 I/O 54 - I/O 59 I/O 60 - I/O 65 I/O 66 - I/O 71 I/O 72 - I/O 77 I/O 78 - I/O 83 I/O 84 - I/O 89 I/O 90 - I/O 95	21, 22, 23, 24, 25, 26 27, 28, 29, 30, 31, 32 34, 35, 36, 37, 38, 39 40, 41, 42, 43, 44, 45 52, 53, 54, 55, 56, 57 58, 59, 60, 61, 62, 63 66, 67, 68, 69, 70, 71 72, 73, 74, 75, 76, 77 85, 86, 87, 88, 89, 90 91, 92, 93, 94, 95, 96 98, 99, 100, 101, 102, 103 104, 105, 106, 107, 108, 109 117, 118, 119, 120, 121, 122 123, 124, 125, 126, 127, 128 2, 3, 4, 5, 6, 7 8, 9, 10, 11, 12, 13	Input/Output Pins - These are the general purpose I/O pins used by the logic array.
GOE0, GOE1	64, 114	Global output enables for all I/Os.
IN 2, IN 4 IN 6 - IN 11	47, 51 84, 110, 111, 115, 116, 14	Dedicated input pins to the device.
$\overline{\text{ispEN}}$	18	Input – Dedicated in-system programming enable input pin. This pin is brought low to enable the programming mode. The MODE, SDI, SDO and SCLK options become active.
SDI/IN 0 <sup>1</sup>	20	Input – This pin performs two functions. It is a dedicated input pin when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as an input pin to load programming data into the device. SDI/IN 0 also is used as one of the two control pins for the isp state machine.
MODE/IN 1 <sup>1</sup>	46	Input – This pin performs two functions. It is a dedicated input pin when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as a pin to control the operation of the isp state machine.
SDO/IN 3 <sup>1</sup>	50	Input/Output – This pin performs two functions. It is a dedicated input pin when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as an output pin to read serial shift register data.
SCLK/IN 5 <sup>1</sup>	78	Input – This pin performs two functions. It is a dedicated input when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as a clock pin for the Serial Shift Register.
$\overline{\text{RESET}}$	19	Active Low (0) Reset pin which resets all of the GLB and I/O registers in the device.
Y0	15	Dedicated Clock input. This clock input is connected to one of the clock inputs of all of the GLBs on the device.
Y1	83	Dedicated clock input. This clock input is brought into the clock distribution network, and can optionally be routed to any GLB on the device.
Y2	80	Dedicated clock input. This clock input is brought into the clock distribution network, and can optionally be routed to any GLB and/or any I/O cell on the device.
Y3	79	Dedicated clock input. This clock input is brought into the clock distribution network, and can optionally be routed to any I/O cell on the device.
GND	1, 17, 33, 49, 65, 81 97, 112	Ground (GND)
VCC	16, 48, 82, 113	V <sub>CC</sub>

1. Pins have dual function capability.

Table 2- 0002C-48C

Pin Description

NAME	CPGA PIN NUMBERS	DESCRIPTION
I/O 0 - I/O 5 I/O 6 - I/O 11 I/O 12 - I/O 17 I/O 18 - I/O 23 I/O 24 - I/O 29 I/O 30 - I/O 35 I/O 36 - I/O 41 I/O 42 - I/O 47 I/O 48 - I/O 53 I/O 54 - I/O 59 I/O 60 - I/O 65 I/O 66 - I/O 71 I/O 72 - I/O 77 I/O 78 - I/O 83 I/O 84 - I/O 89 I/O 90 - I/O 95	J2, J3, K1, L1, K2, M1, L2, K3, N1, M2, L3, P1, M3, P2, N3, M4, P3, N4, P4, M5, N5, P5, M6, N6, N9, M9, P10, P11, N10, P12, N11, M10, P13, N12, M11, P14, M12, N14, M13, L12, M14, L13, L14, K12, K13, K14, J12, J13, F13, F12, E14, D14, E13, C14, D13, E12, B14, C13, D12, A14, C12, A13, B12, C11, A12, B11, A11, C10, B10, A10, C9, B9, B6, C6, A5, A4, B5, A3, B4, C5, A2, B3, C4, A1, C3, B1, C2, D3, C1, D2, D1, E3, E2, E1, F3, F2	Input/Output Pins - These are the general purpose I/O pins used by the logic array.
GOE0, GOE1	N13, B7,	Global output enables for all I/Os.
IN 2, IN 4 IN 6 - IN 11	P7, P9 F14, A9, A8, A7, A6, F1	Dedicated input pins to the device.
$\overline{\text{ispEN}}$	H2	Input – Dedicated in-system programming enable input pin. This pin is brought low to enable the programming mode. The MODE, SDI, SDO and SCLK options become active.
SDI/IN 0 <sup>1</sup>	J1	Input – This pin performs two functions. It is a dedicated input pin when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as an input pin to load programming data into the device. SDI/IN 0 also is used as one of the two control pins for the isp state machine.
MODE/IN 1 <sup>1</sup>	P6	Input – This pin performs two functions. It is a dedicated input pin when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as a pin to control the operation of the isp state machine.
SDO/IN 3 <sup>1</sup>	P8	Input/Output – This pin performs two functions. It is a dedicated input pin when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as an output pin to read serial shift register data.
SCLK/IN 5 <sup>1</sup>	J14	Input – This pin performs two functions. It is a dedicated input when $\overline{\text{ispEN}}$ is logic high. When $\overline{\text{ispEN}}$ is logic low, it functions as a clock pin for the Serial Shift Register.
RESET	H1	Active Low (0) Reset pin which resets all of the GLB and I/O registers in the device.
Y0	G1	Dedicated Clock input. This clock input is connected to one of the clock inputs of all of the GLBs on the device.
Y1	G14	Dedicated clock input. This clock input is brought into the clock distribution network, and can optionally be routed to any GLB on the device.
Y2	H13	Dedicated clock input. This clock input is brought into the clock distribution network, and can optionally be routed to any GLB and/or any I/O cell on the device.
Y3	H14	Dedicated clock input. This clock input is brought into the clock distribution network, and can optionally be routed to any I/O cell on the device.
GND	B2, B8, B13, C8, H3, H12, M8, N2, N8	Ground (GND)
VCC	C7, G2, G3, G12, G13, M7, N7	V <sub>cc</sub>

1. Pins have dual function capability.

Table 2- 0002C-48C/CPGA

Pin Configuration

ispLSI 1048C 128-Pin PQFP Pinout Diagram



Pin Configuration

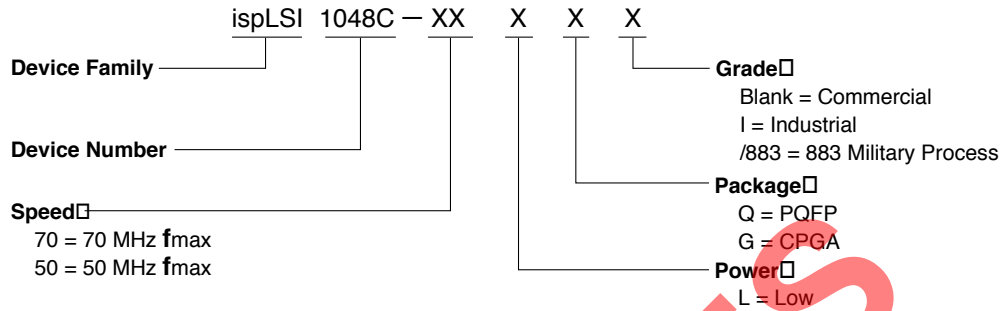
ispLSI 1048C 133-Pin CPGA Pinout Diagram



1. Pins have dual function capability.

133 CPGA Pinout.eps

Part Number Description



Ordering Information

**COMMERCIAL**

Family	$f_{max}$ (MHz)	$t_{pd}$ (ns)	Ordering Number	Package
ispLSI	70	16	ispLSI 1048C-70LQ	128-Pin PQFP
	50	22	ispLSI 1048C-50LQ	128-Pin PQFP

**INDUSTRIAL**

Family	$f_{max}$ (MHz)	$t_{pd}$ (ns)	Ordering Number	Package
ispLSI	50	22	ispLSI 1048C-50LQI	128-Pin PQFP



**MILITARY**

Family	$f_{max}$ (MHz)	$t_{pd}$ (ns)	Ordering Number	SMD Number	Package
ispLSI	50	22	ispLSI 1048C-50LG/883	5962-9558701MXC	133-Pin CPGA

Table 2- 0041A-48C-isp

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